

Features

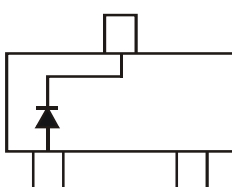
- Low Forward Voltage Drop
- Fast Switching
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

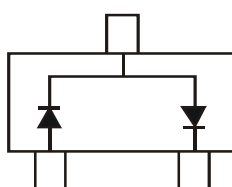
- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208 **(e3)**
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Weight: 0.008 grams (approximate)



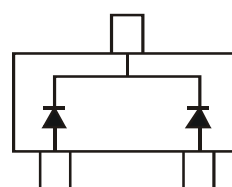
Top View



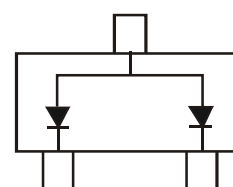
BAS40



BAS40-04



BAS40-05



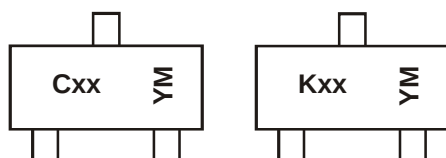
BAS40-06

Ordering Information (Note 4 & 5)

Part Number	Case	Packaging
BAS40-7-F	SOT23	3000/Tape & Reel
BAS40-04-7-F	SOT23	3000/Tape & Reel
BAS40-05-7-F	SOT23	3000/Tape & Reel
BAS40-06-7-F	SOT23	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.
 5. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

Marking Information



K=(SAT,Shanghai Assembly / test site)
 C=(CAT / DTC , ChengDu Assembly / test site)
 xx = Product Type Marking Code:
 43 = BAS40
 44 = BAS40-04
 45 = BAS40-05
 46 = BAS40-06
 YM = Date Code Marking
 Y = Year (ex: T = 2006)
 M = Month (ex: 9 = September)

Date Code Key

Year	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	K	L	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec					
Code	1	2	3	4	5	6	7	8	9	O	N	D					

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Forward Continuous Current (Note 6)	I _{FM}	200	mA
Forward Surge Current (Note 6) @ t < 1.0s	I _{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	357	°C/W
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	40	—	—	V	I _R = 10μA
Forward Voltage	V _F	—	—	380 1000	mV	t _p < 300μs, I _F = 1.0mA t _p < 300μs, I _F = 40mA
Reverse Leakage Current (Note 7)	I _R	—	20	200	nA	t _p < 300μs, V _R = 30V
Total Capacitance	C _T	—	4.0	5.0	pF	V _R = 0V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	5.0	ns	I _F = I _R = 10mA to I _R = 1.0mA, R _L = 100Ω

Notes: 6. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 7. Short duration pulse test used to minimize self-heating effect.

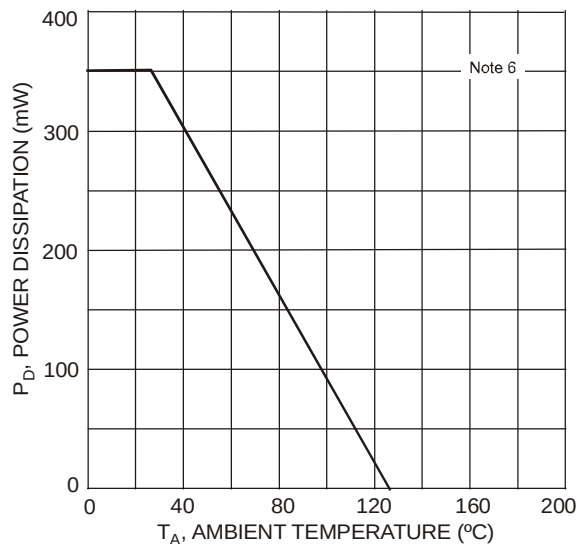


Figure 1 Power Derating Curve, Total Package

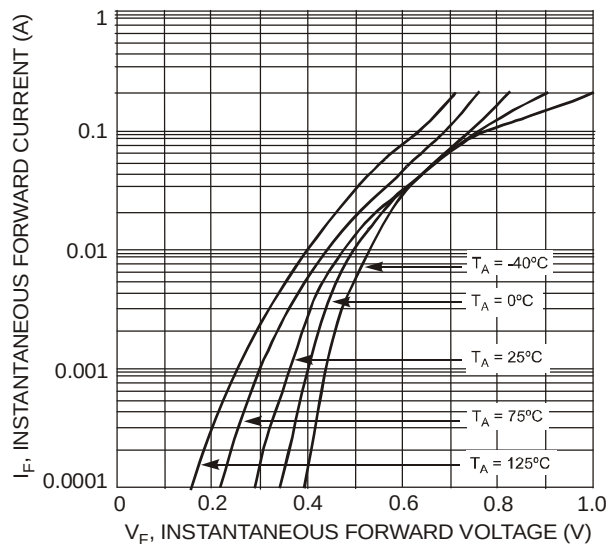


Figure 2 Typical Forward Characteristics

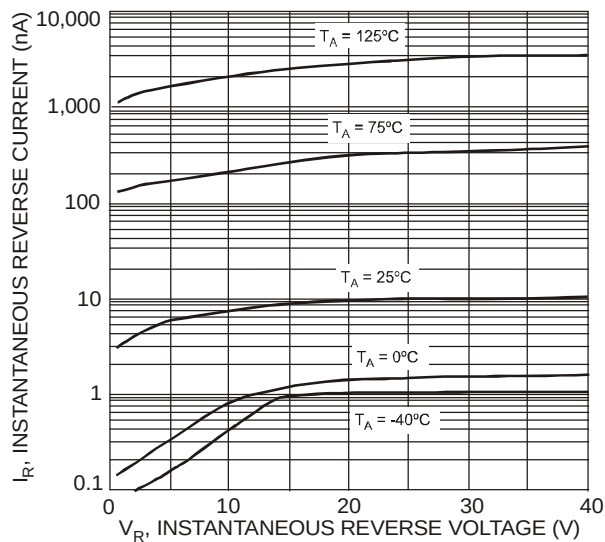


Figure 3 Typical Reverse Characteristics

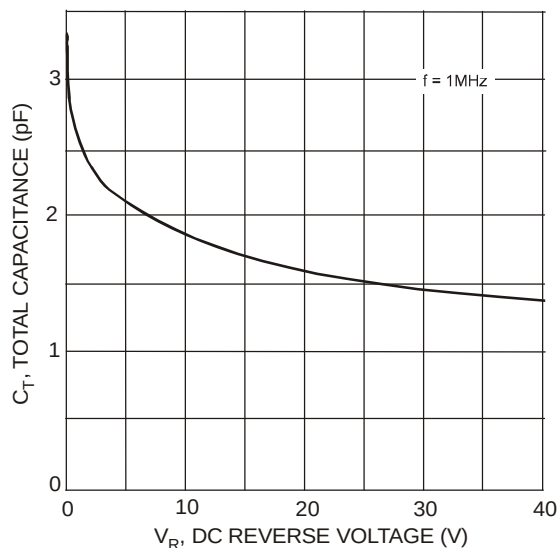
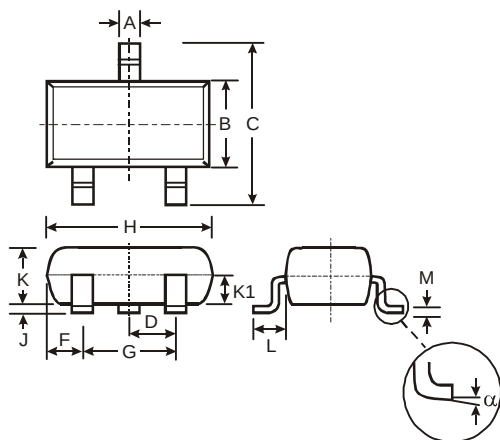


Figure 4 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

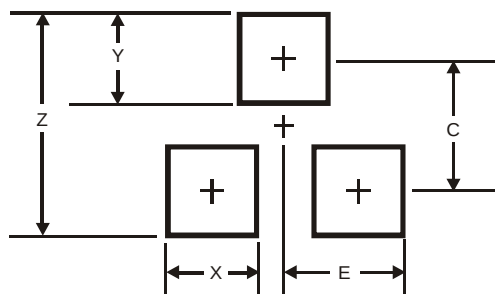
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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